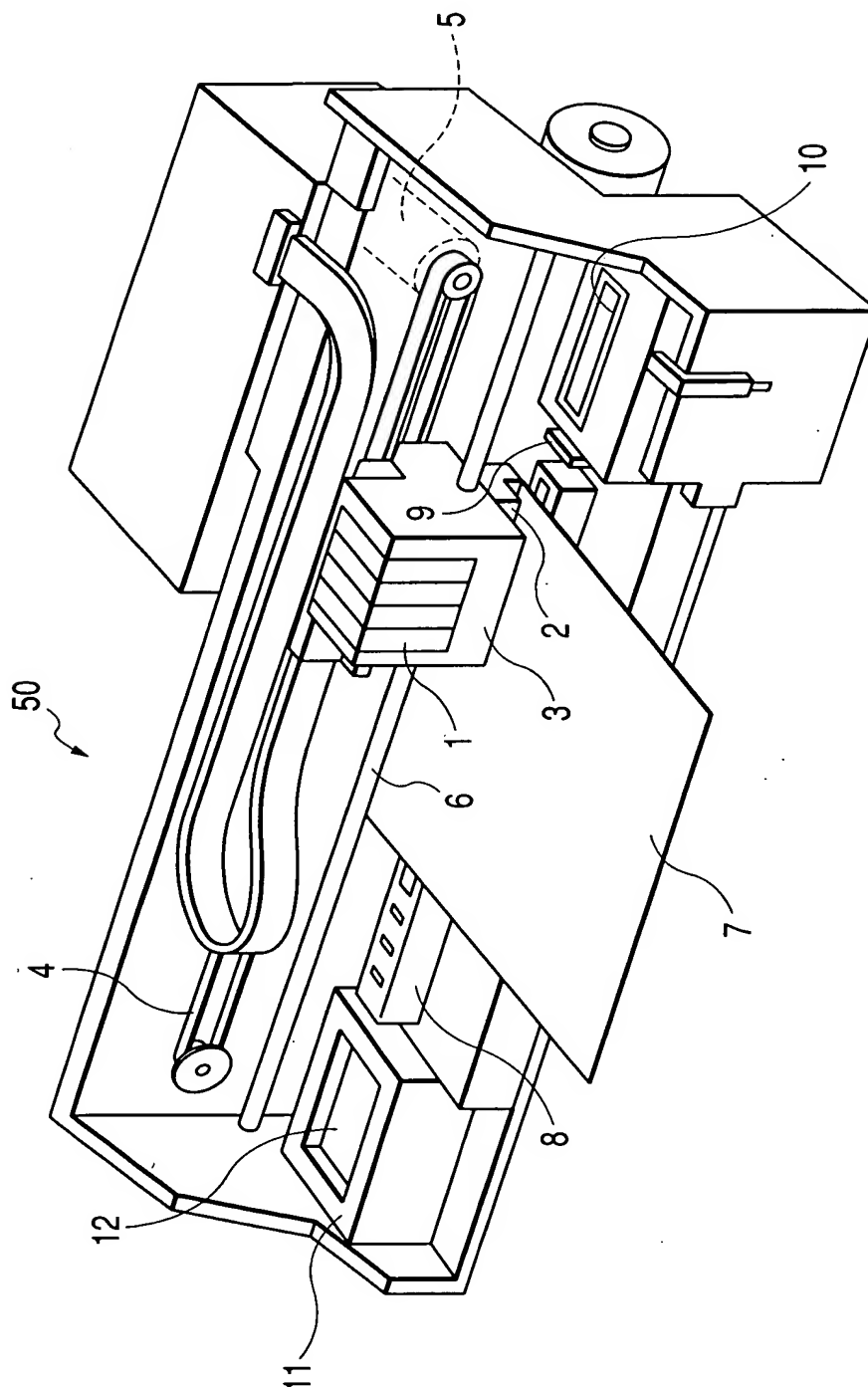
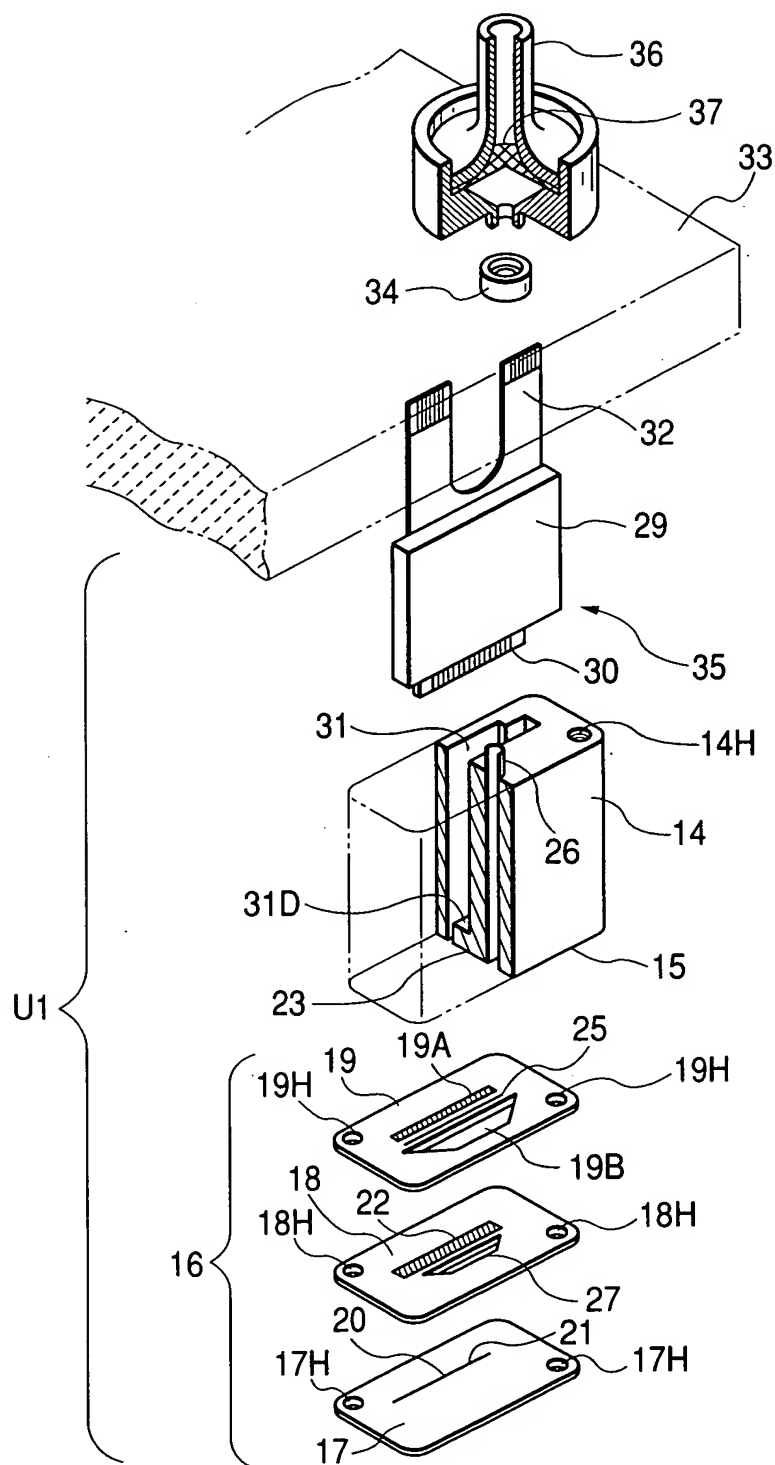


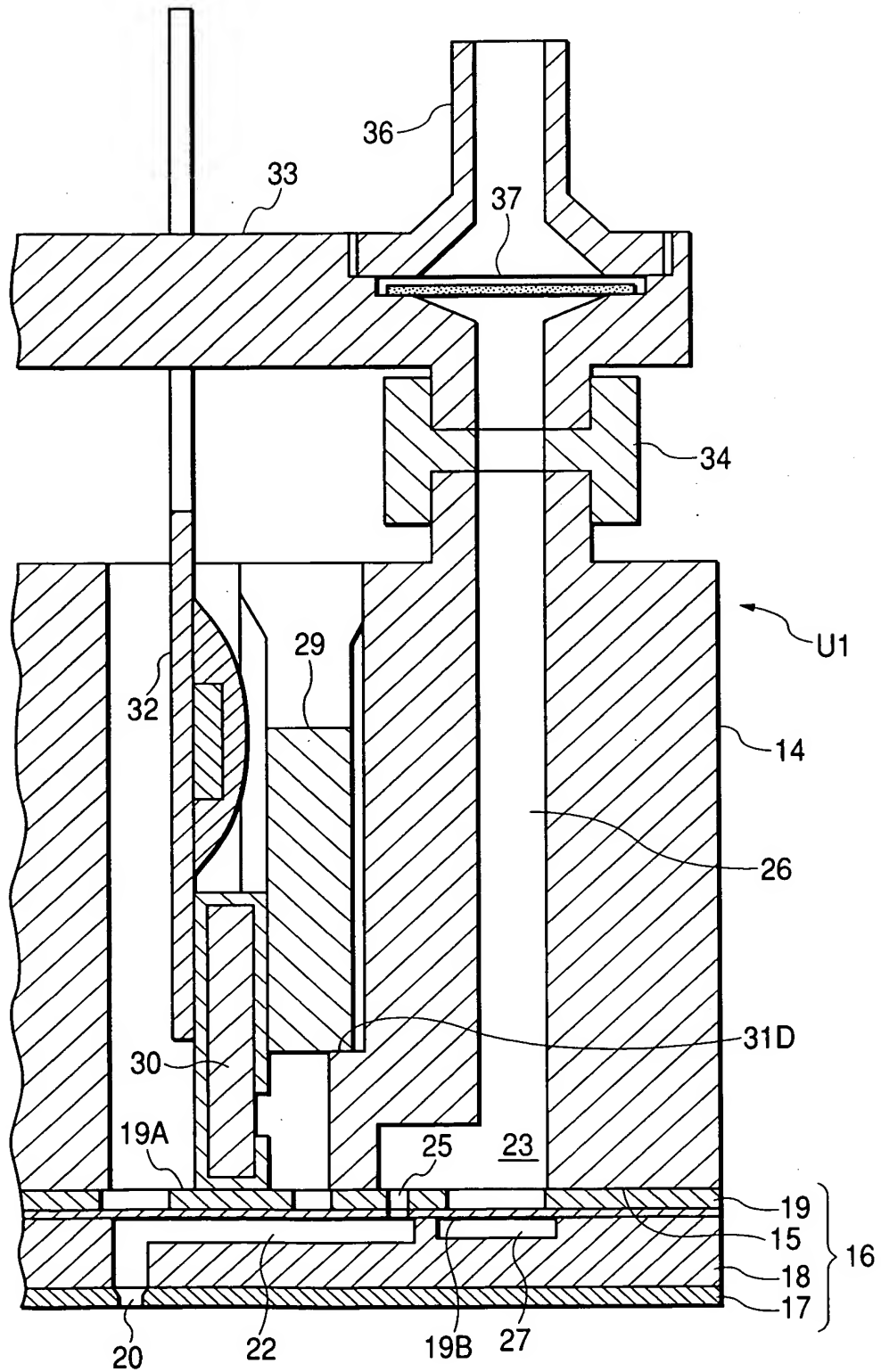
**FIG. 1**



**FIG. 2**

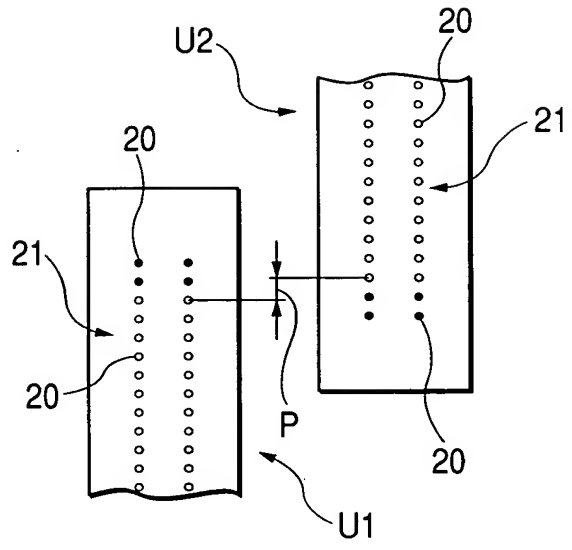


**FIG. 3**



[illegible]

**FIG. 5B**

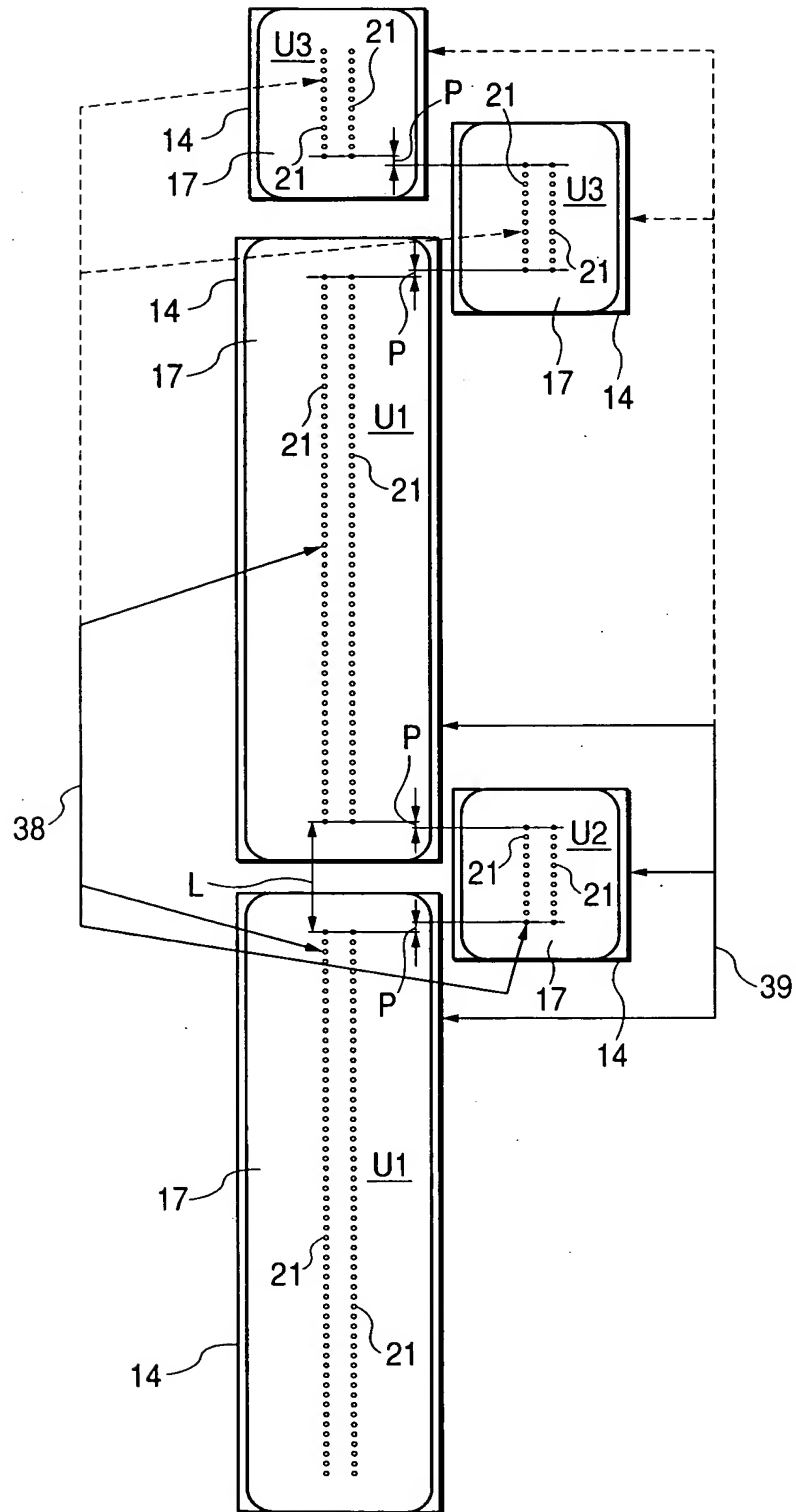


**FIG. 6A**

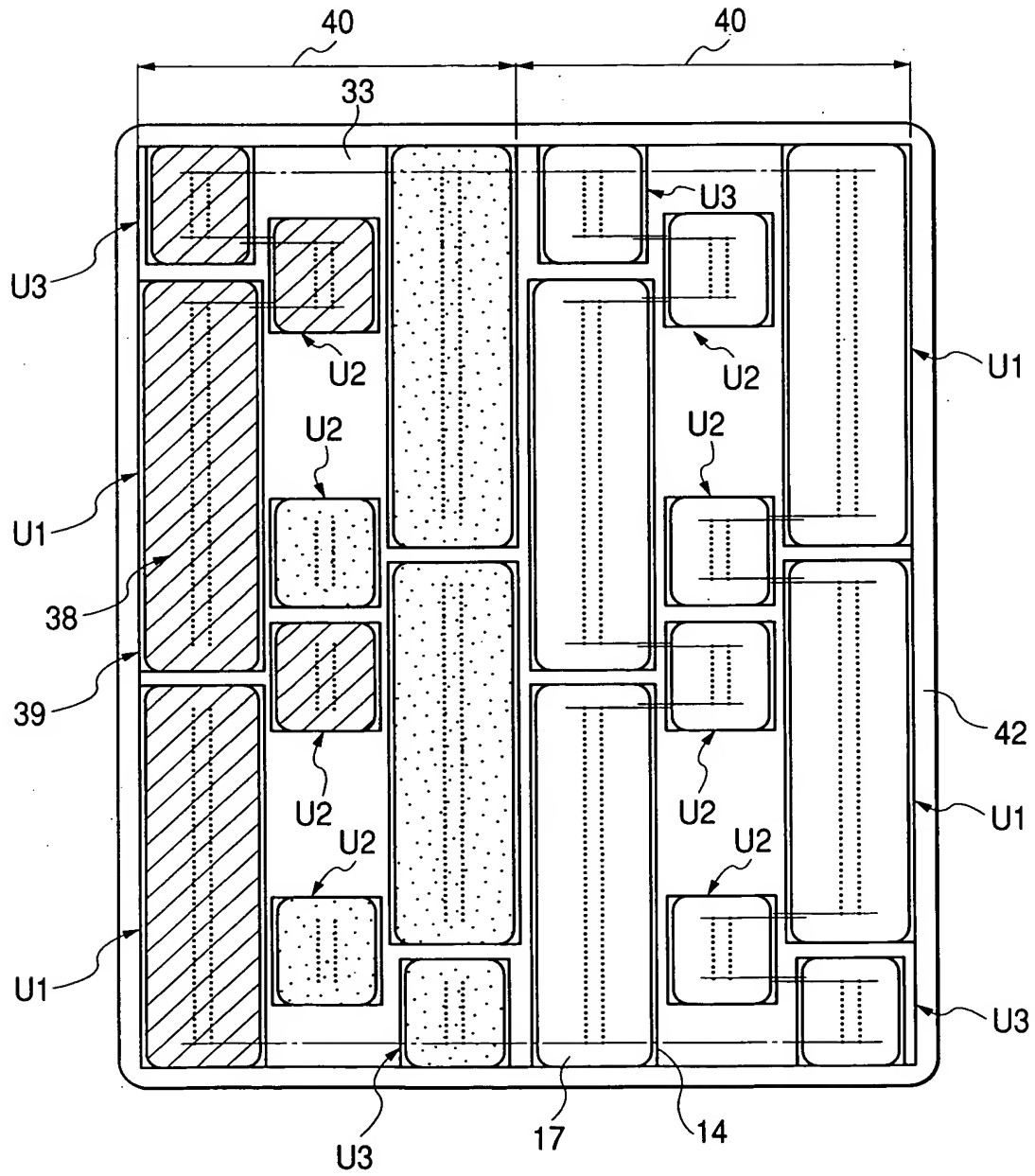
FIG. 6A is a schematic diagram of a multi-layered structure 40, shown in a cross-sectional view. The structure 40 is composed of several layers and components. On the left side, there is a hatched layer 33. To its right is a layer 38, which contains a vertical dashed line. Further right is a layer 39, which contains a vertical dashed line. The central part of the structure 40 is divided into two main sections. The left section contains a layer 17, which is a solid layer. To its right is a layer 21, which is a dotted layer. The right section contains a layer 17, which is a solid layer. To its right is a layer 21, which is a dotted layer. The rightmost part of the structure 40 is a layer 42, which is a solid layer. Various components are labeled with 'U' and numbers: U1, U2, and U3 are labels for specific components within the layers. U1 is located in the hatched layer 33, the solid layer 17, and the dotted layer 21. U2 is located in the solid layer 17. U3 is located in the dotted layer 21. The labels 17 and 21 are also used to identify the solid and dotted layers, respectively. The label 42 is used to identify the rightmost solid layer.

Diagram 3 shows two sheets 39 joined at a central line. The sheets have wavy edges 20 and 21. A pressure  $P/2$  is applied to the central line, and a pressure  $P$  is applied to the outer edges.

**FIG. 7**

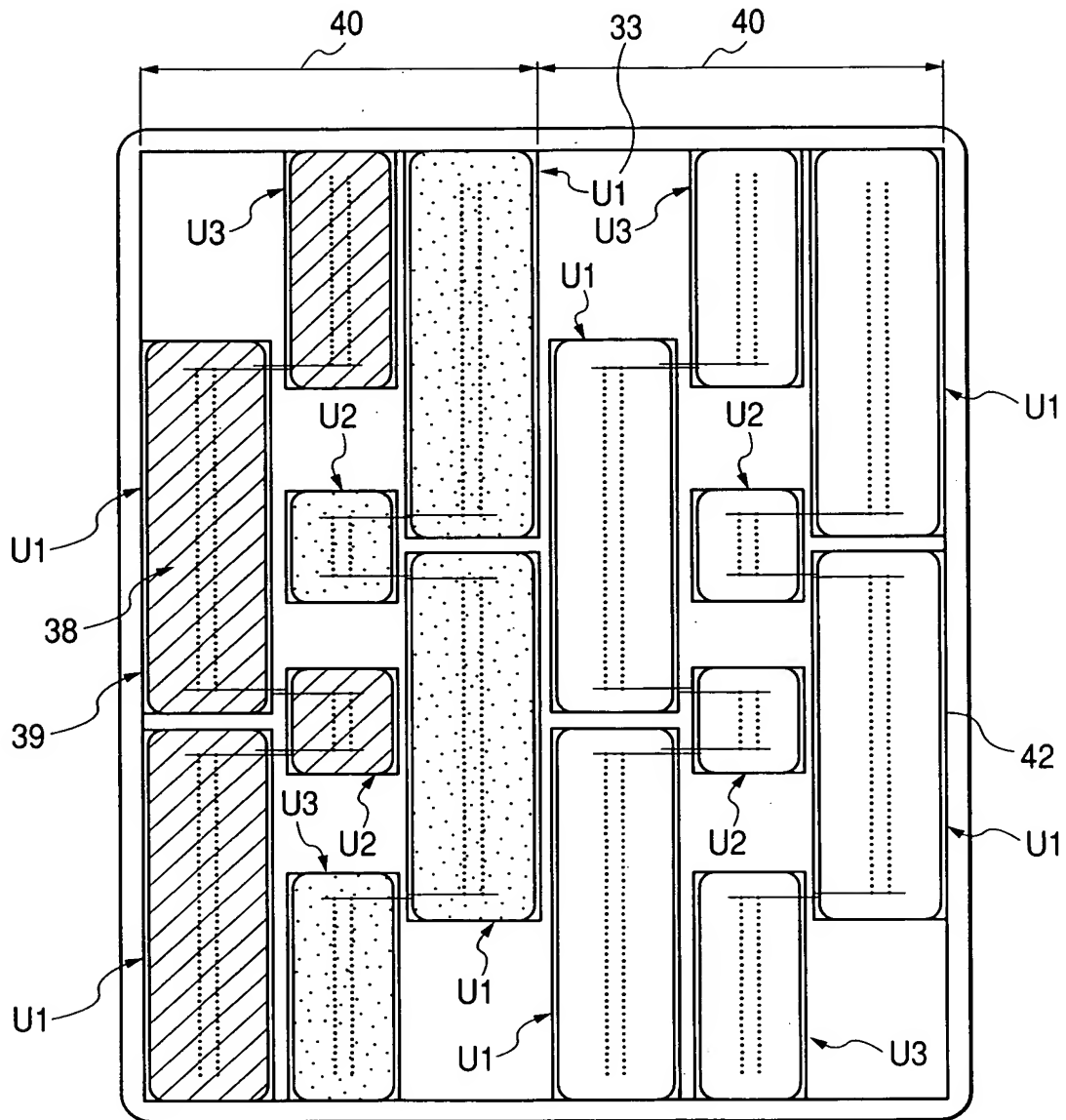


**FIG. 8**

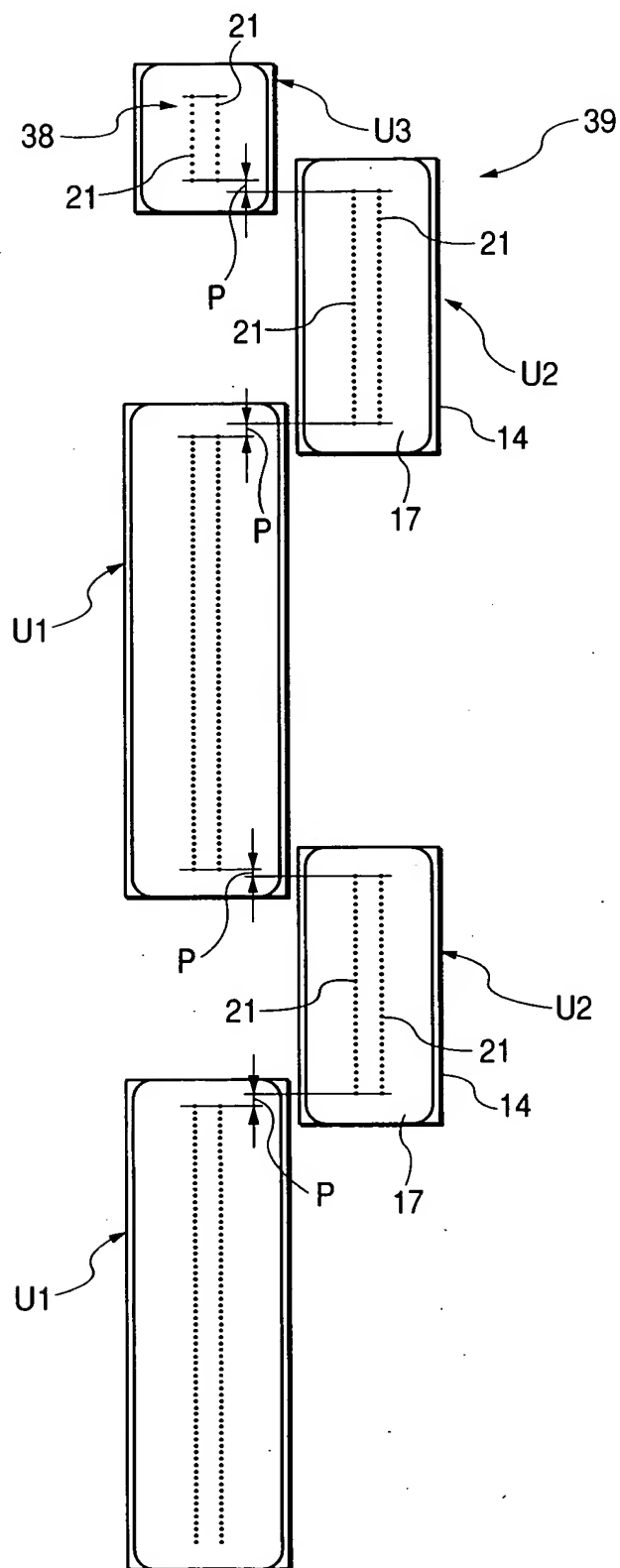




**FIG. 9**



**FIG. 10**



**FIG. 11**

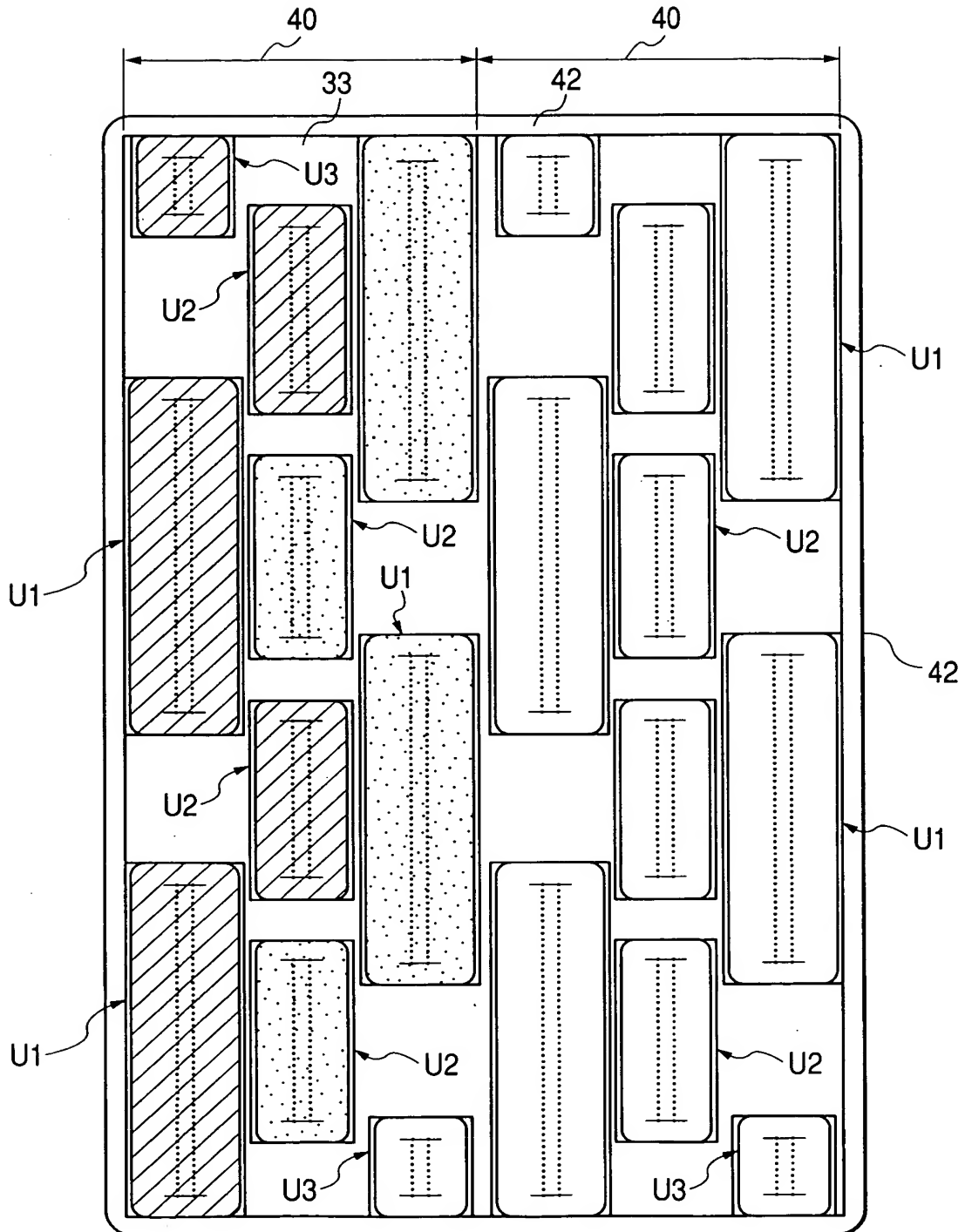
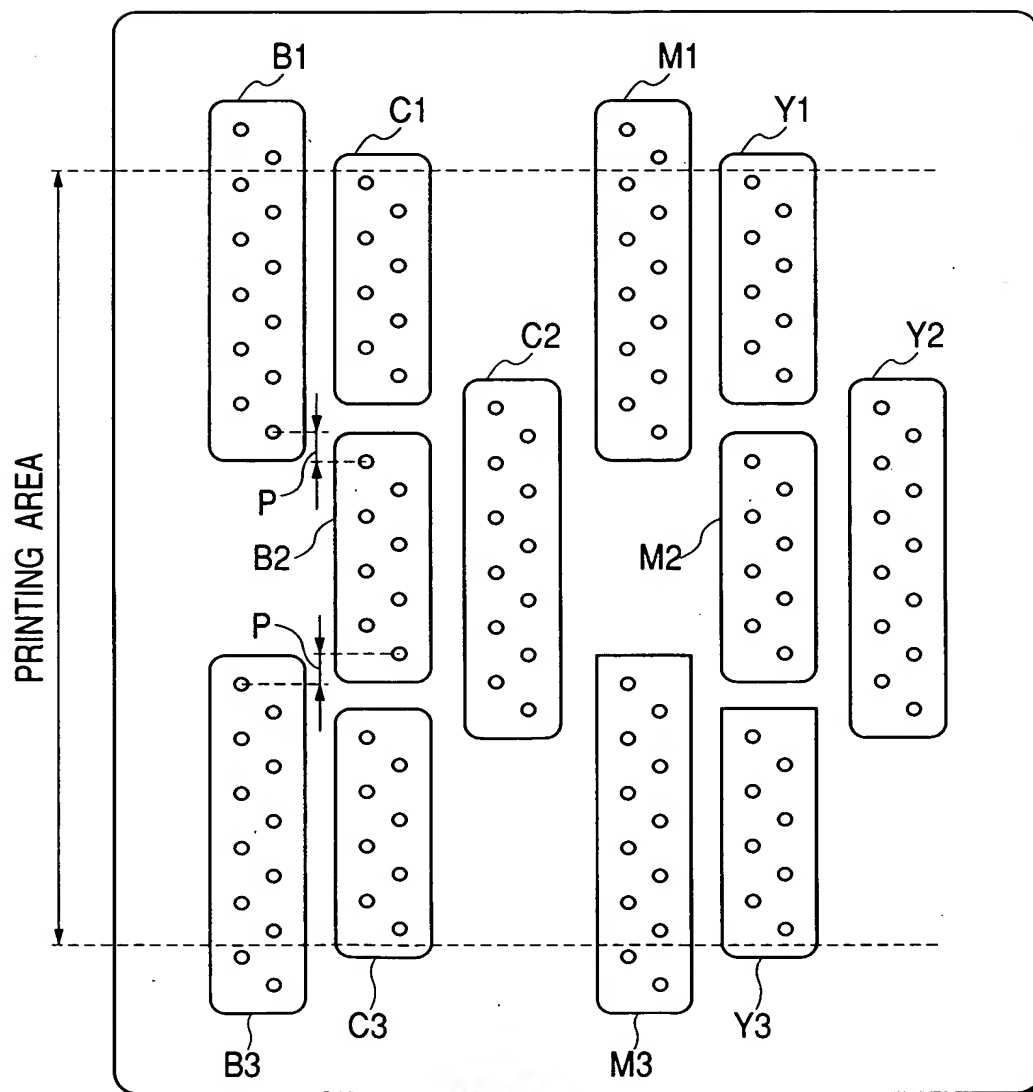


FIG. 1 is a schematic cross-sectional view of a semiconductor device. The device consists of two main regions, each containing a stack of layers. The left region includes a p-type layer (P) at the top, followed by layers 43, 44, and 45. The right region also includes a p-type layer (P) at the top, followed by layers 43, 44, and 45. Various other labels are present: U1 points to the outermost layers; U2 points to the interface between layers 44 and 45; U3 points to the top surface; 12A and 12B point to specific interfaces or features; 33 points to the top boundary; 40 and 42 point to the overall structure; 43, 44, and 45 label different material layers; and 46 labels a central vertical structure.

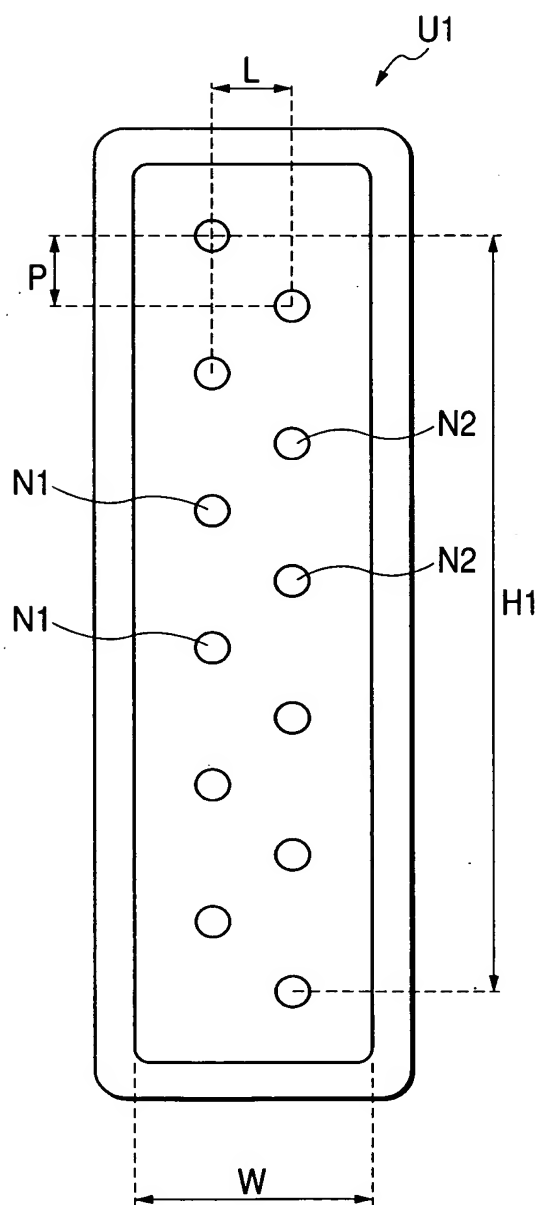
A cross-sectional view of a semiconductor device. A substrate 33 is at the base. Two U-shaped regions, labeled U1, are formed in the substrate. The left U-shaped region has a side wall 43 and a bottom 45. The right U-shaped region has a side wall 42 and a bottom 45. Both U-shaped regions are filled with a material indicated by diagonal hatching. On top of each U-shaped region, there is a structure 16, which appears to be a multi-layered cap or contact layer.

Fig. 1 is a cross-sectional view of a semiconductor device. The device includes a substrate 33, a base layer 42, a gate stack 43, and a gate electrode 16. A channel region 44 is defined within the substrate 33.

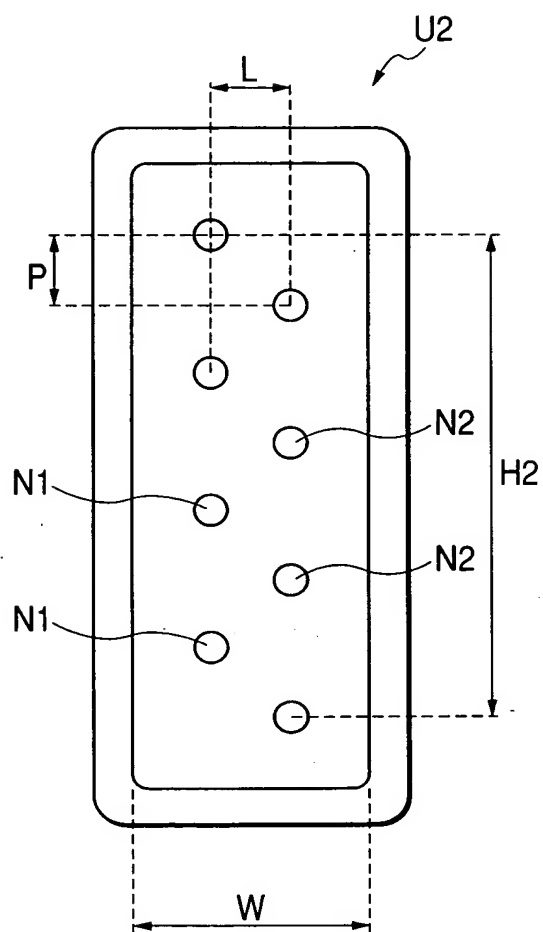
**FIG. 14**



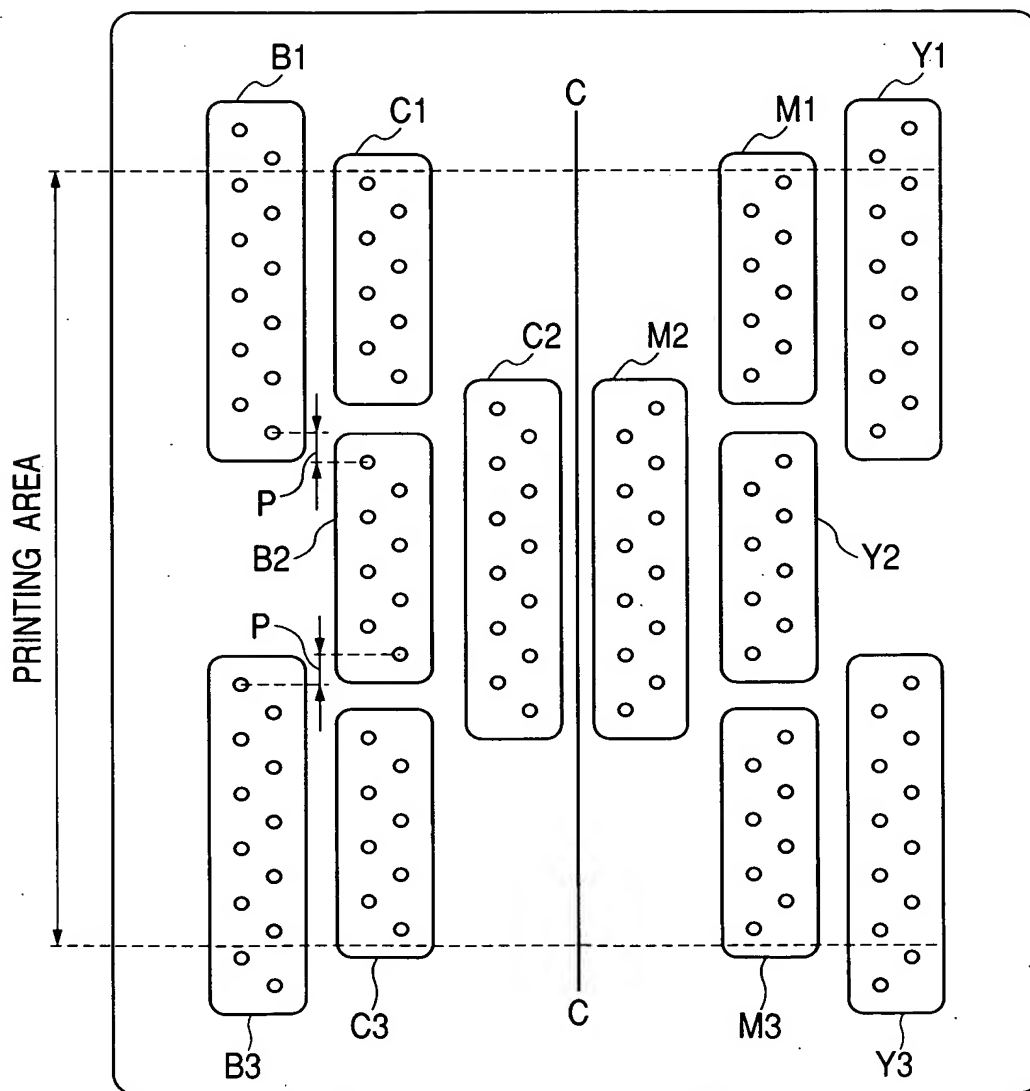
**FIG. 15A**



**FIG. 15B**

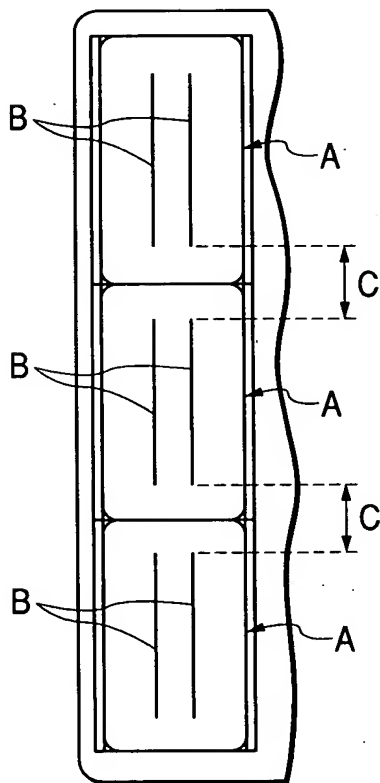


**FIG. 16**

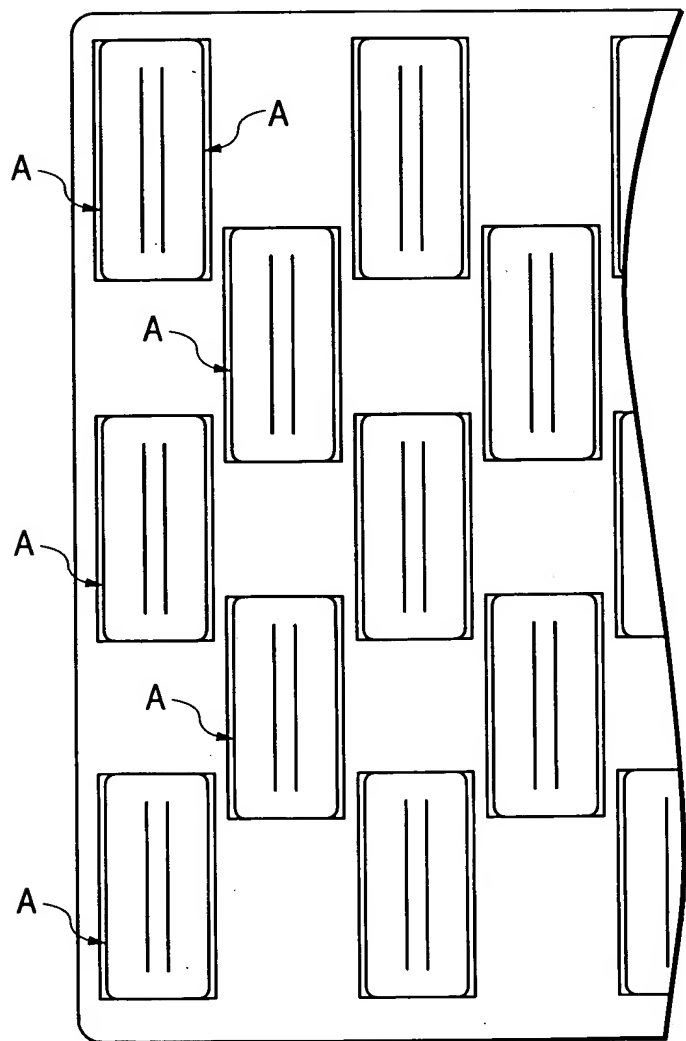




**FIG. 17A**



**FIG. 17B**



This exploded perspective view illustrates the assembly of a multi-layered electronic device. The components are labeled as follows:

- 36**: A cylindrical component with a central protrusion, shown in two views.
- 37**: A ring-shaped component with a central opening.
- 33**: A small cylindrical component.
- 34**: A small cylindrical component with a flange.
- 32**: A rectangular component with a central slot.
- 29**: A rectangular component with a central slot.
- 35**: A small cylindrical component.
- 30**: A rectangular component with a central slot.
- 31**: A rectangular component with a central slot.
- 14**: A rectangular component with a central slot.
- 26**: A rectangular component with a central slot.
- 31D**: A rectangular component with a central slot.
- 15**: A rectangular component with a central slot.
- 19**: A rectangular component with a central slot.
- 23**: A rectangular component with a central slot.
- 25**: A rectangular component with a central slot.
- 19A**: A rectangular component with a central slot.
- 27**: A rectangular component with a central slot.
- 22**: A rectangular component with a central slot.
- 18**: A rectangular component with a central slot.
- 20**: A rectangular component with a central slot.
- 21**: A rectangular component with a central slot.
- 17**: A rectangular component with a central slot.